

# Ductile Void Nucleation in Pure BCC Metals under Quasi-static Loading

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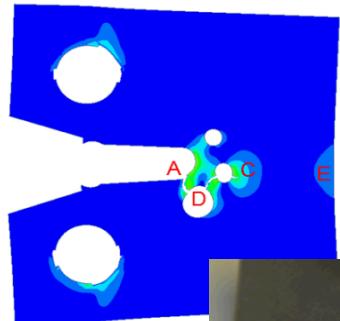
June, 2017

Int. Conf. on Fracture

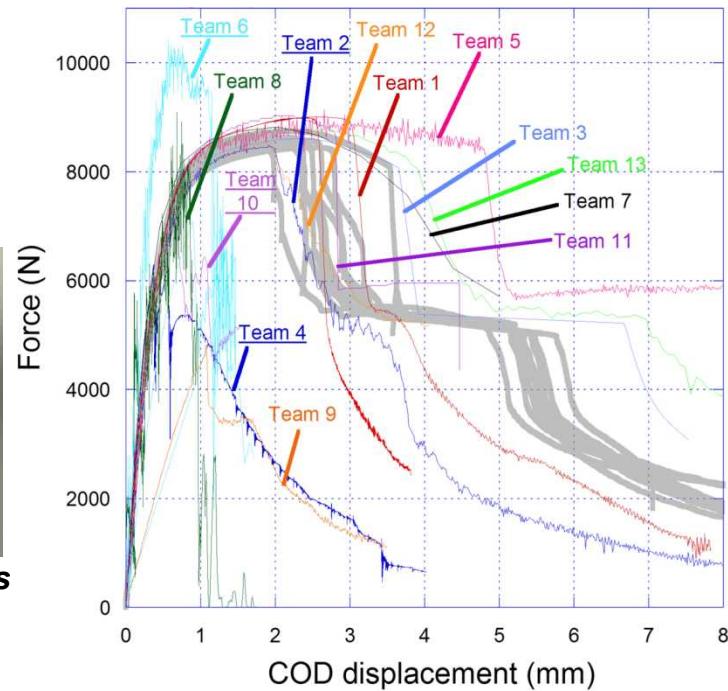
# *The Sandia Fracture Challenge explores the limits of ductile failure prediction*



## Special Issues in 2014 & 2016



We have built an **International Consortium of >30 volunteer organizations**



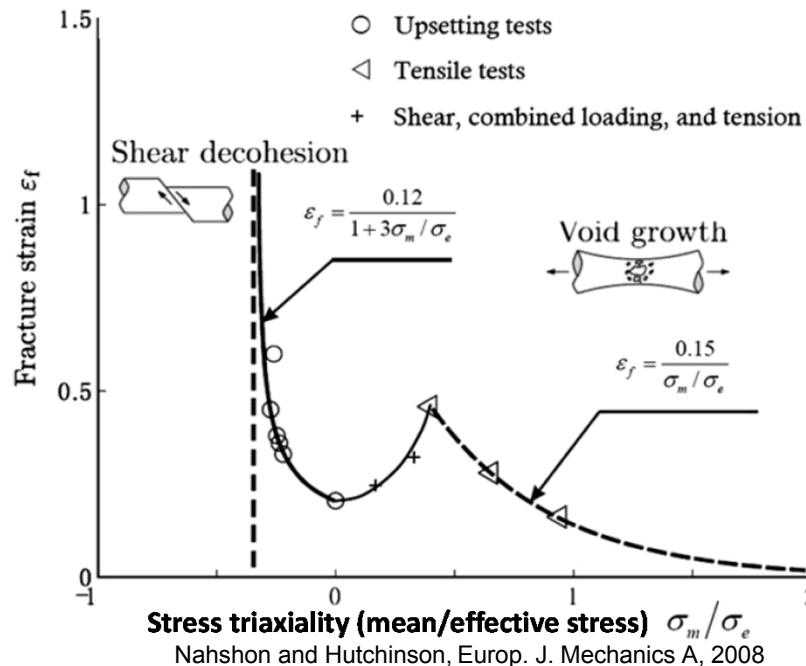
- Lack of consensus on the governing equation for void rupture
- Deterministic methods struggle with microstructurally rare events
- State of the art involves empirical continuum models

# Models for void nucleation are largely empirical

$$\dot{\phi} = \sqrt{\frac{2}{3}} \dot{\epsilon}_p \frac{1 - (1 - \phi)^{m+1}}{(1 - \phi)^m} \cdot \sinh \left[ \frac{2(2m-1)}{2m+1} \frac{\langle p \rangle}{\sigma_e} \right] + (1 - \phi)^2 \dot{\eta} v_{vo}.$$

Void growth

Void nucleation



## Additional nucleation models

Gurland and Plateau, 1963

Ashby, 1966

Coleman and Gurtin, 1967

Rosenfield, 1968

Barbee et al., 1972

Argon et al., 1975

Raj and Ashby, 1975

Gurson, 1977a, b

Needleman and Rice, 1978

Goods and Brown, 1979

Tvergaard, 1982a

Saje et al, 1982

Hirth and Nix, 1985

$$\dot{\eta} = \eta \dot{\epsilon}_p \left\{ N_1 \left[ \frac{4}{27} - \frac{J_3^2}{J_2^3} \right] + N_2 \frac{J_3}{J_2^{3/2}} + N_3 \left\| \frac{I_1}{\sqrt{J_2}} \right\| \right\} N_4$$

Void nucleation rate

Fitting parameters

void content

strain-rate

stress state descriptors

Horstemeyer and Gokhale, Int. J. Solids. Struct., 1999

# Vacancy Condensation

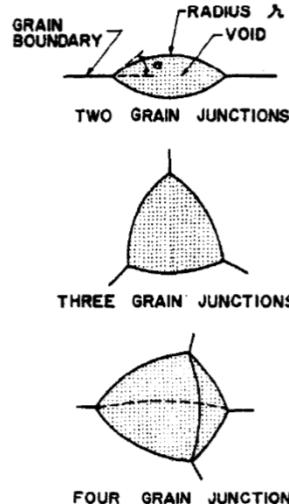
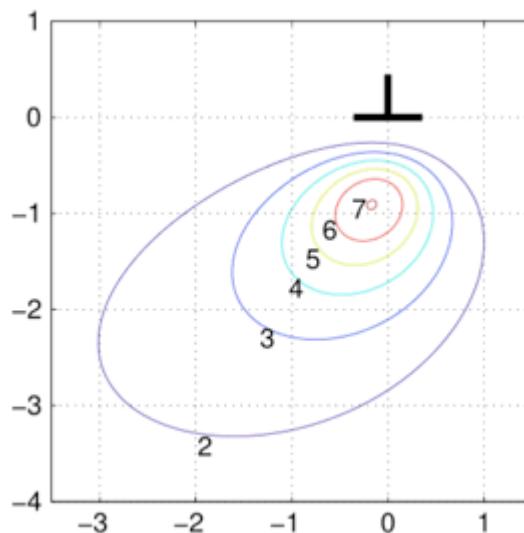


FIG. 1. Void geometries in inclusion-free grain boundaries.

Raj and Ashby, Acta Metallurgica, 1975



Sills and Cai, Phil. Mag., 2016

Voids are thought to form by vacancy condensation at **grain boundaries** (Raj and Ashby, 1975)

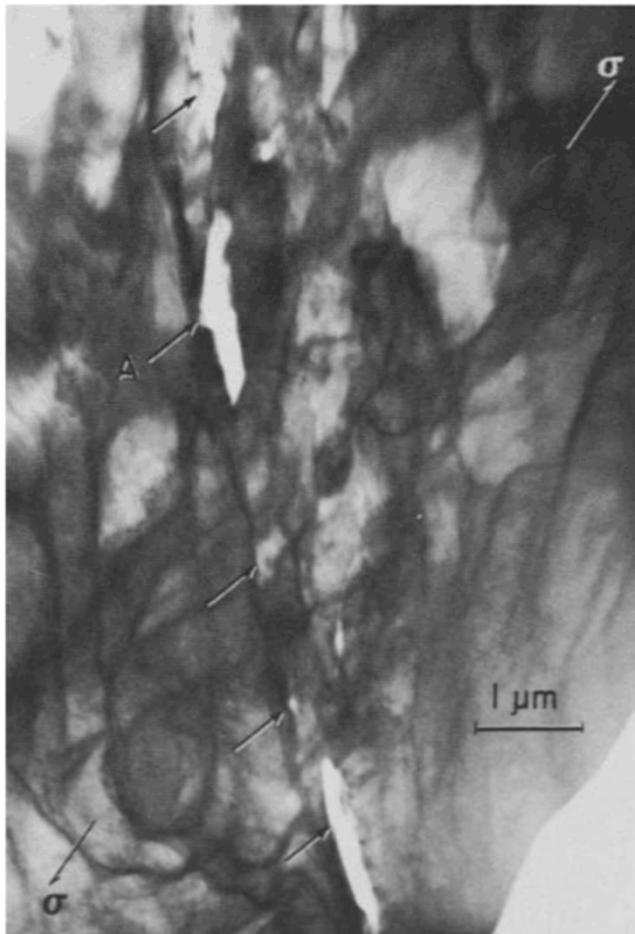
At lower temperature, is thought to require high hydrostatic tensile stress (inherently difficult to observe at free surfaces)

When vacancy sources and sinks are present, requisite stress is substantially lower (Hirth and Nix 1985).

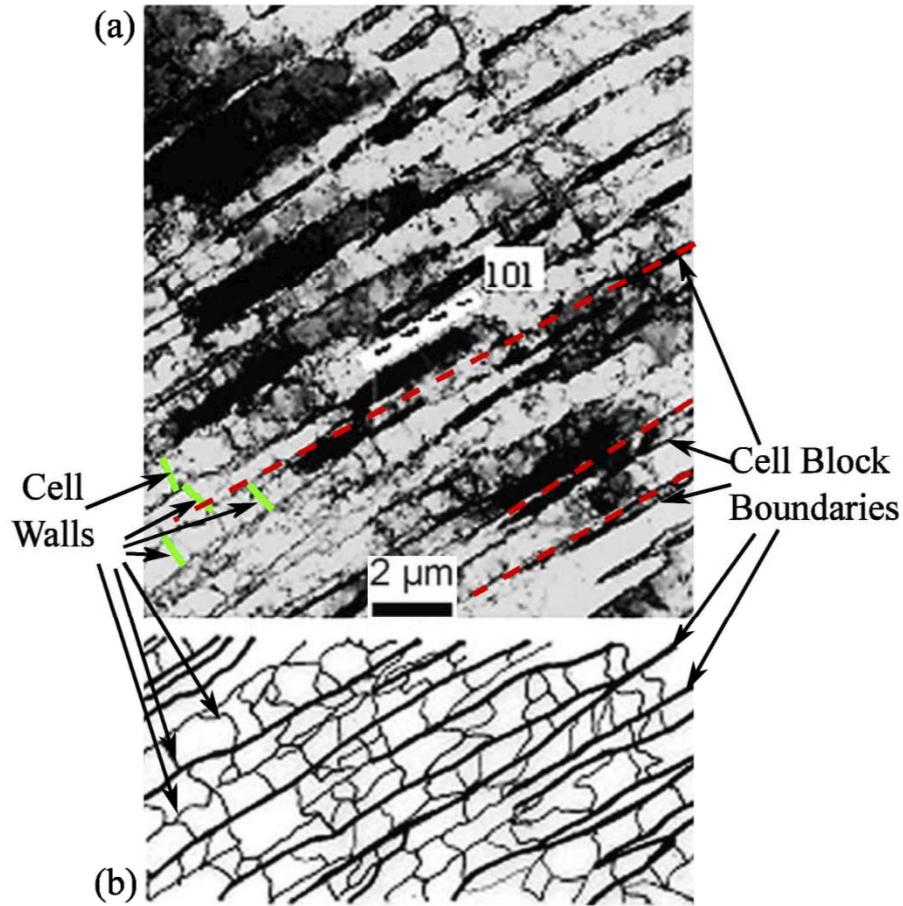
Dislocation climb is a potential vacancy source at high temperatures

Gliding dislocations drag solute, and by extension vacancies (Sills and Cai, Phil Mag, 2016)

# Tools and Understanding of Microstructure have improved over the past 30+ years

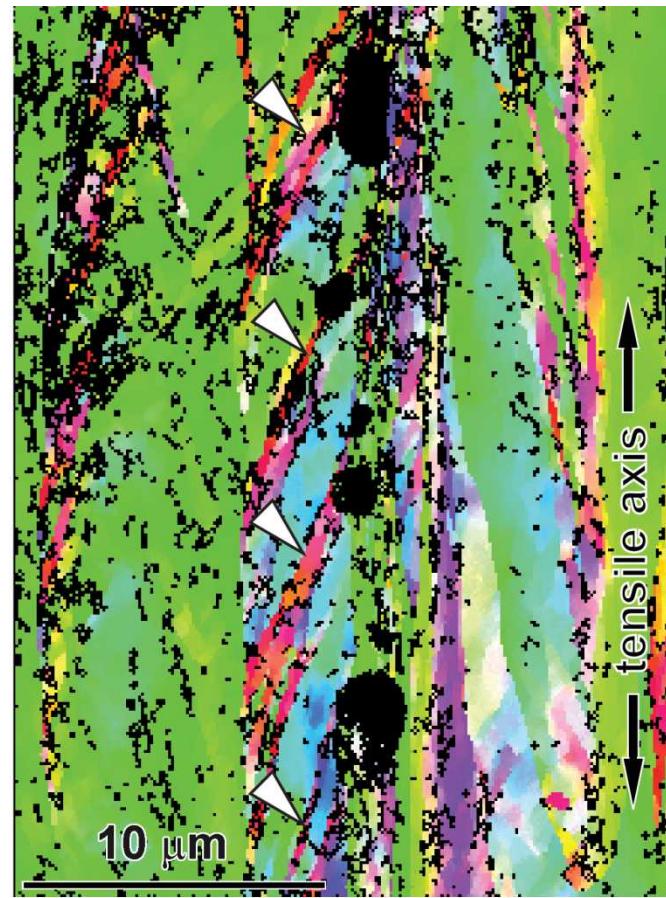
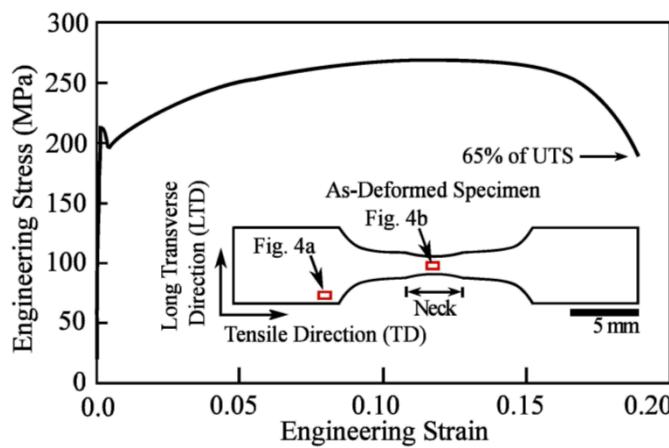


R. N. Gardner, T. C. Pollock, and H. Wilsdorf, "Crack initiation at dislocation cell boundaries in the ductile fracture of metals," *Materials Science and Engineering*, vol. 29, no. 2, pp. 169-174, 1977.



B. Li, A. Godfrey, Q. Meng, Q. Liu, and N. Hansen, "Microstructural evolution of if-steel during cold rolling," *Acta Materialia*, vol. 52, no. 4, pp. 1069-1081, 2004.

Interrupted tension +  
Cross-sectional metallography  
+ EBSD



From Boyce et al., *Metall. Mater. Trans. A*, 2013

**Hypothesis:** void nucleation under tension in pure metals occurs when the dislocation network forms intense cell walls that are detected as high-angle subgrain boundaries.

## “Treasure Hunt”

99.9% Ta deformed to 40% UTS

Visible Surface  
→

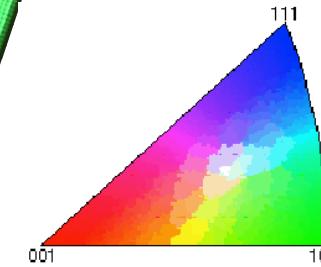
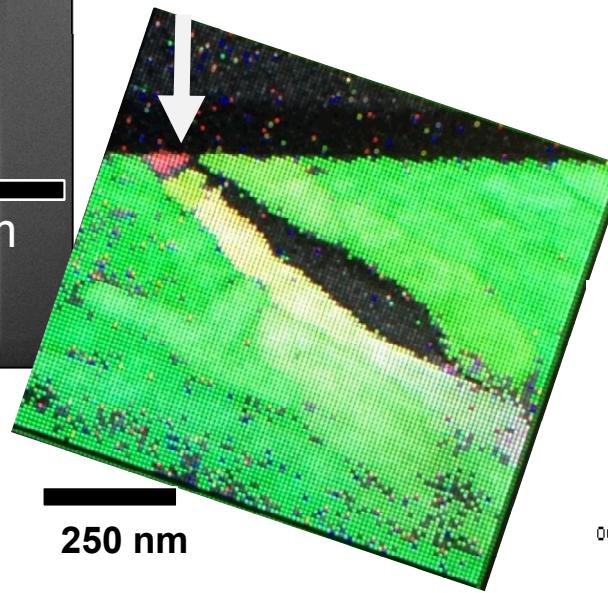
100  $\mu\text{m}$

3  $\mu\text{m}$

250

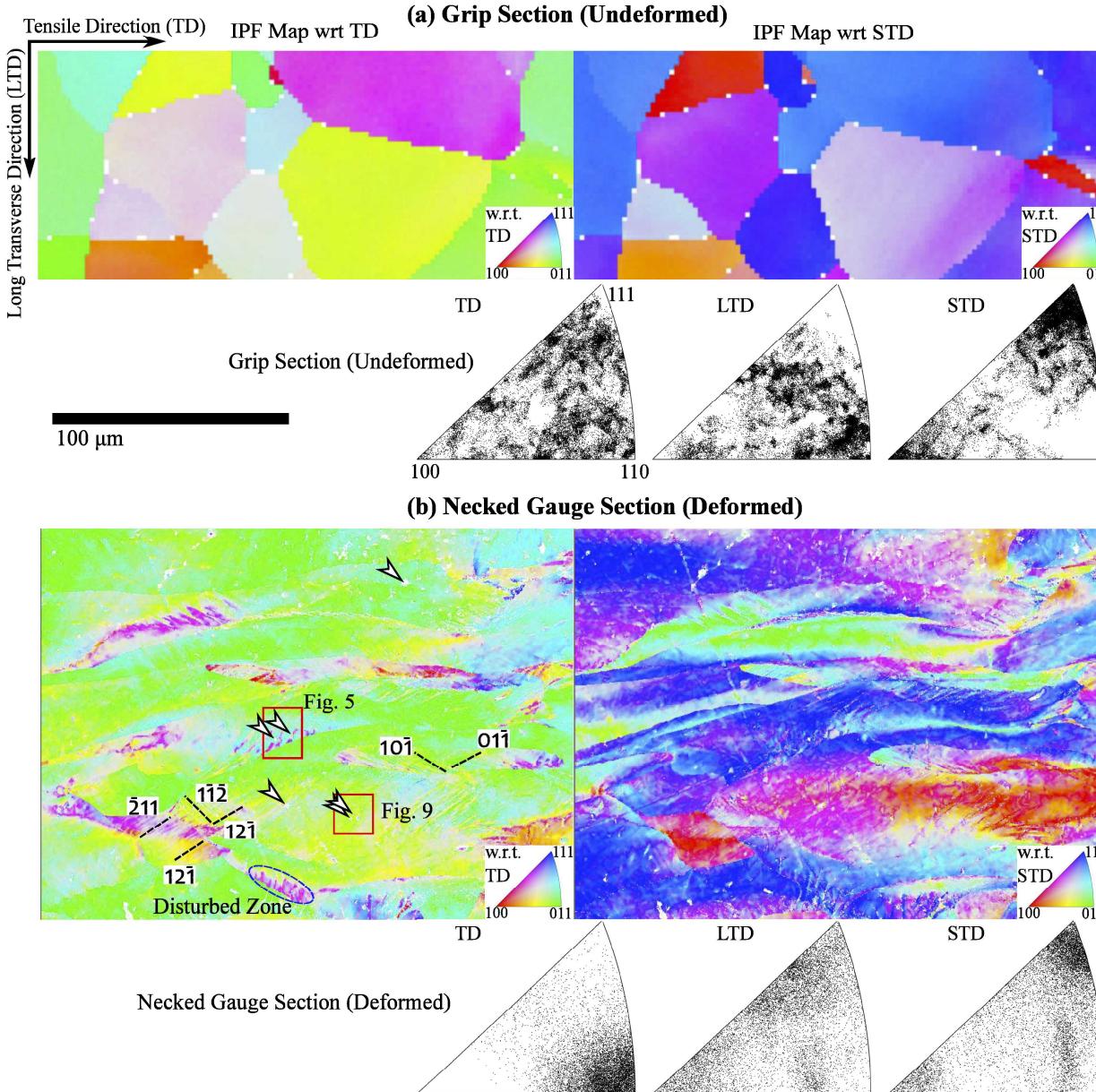
250 nm

- Focused Ion Beam (FIB) used to locate subsurface, deformation-induced voids in interrupted tensile bar.
- Void shape is aligned with subgrain boundaries.
- Transmission Kikuchi Diffraction (TKD) to determine crystallographic orientation near void.
- Orientations are consistent with EBSD analysis showing void nucleation along high angle misorientation boundaries

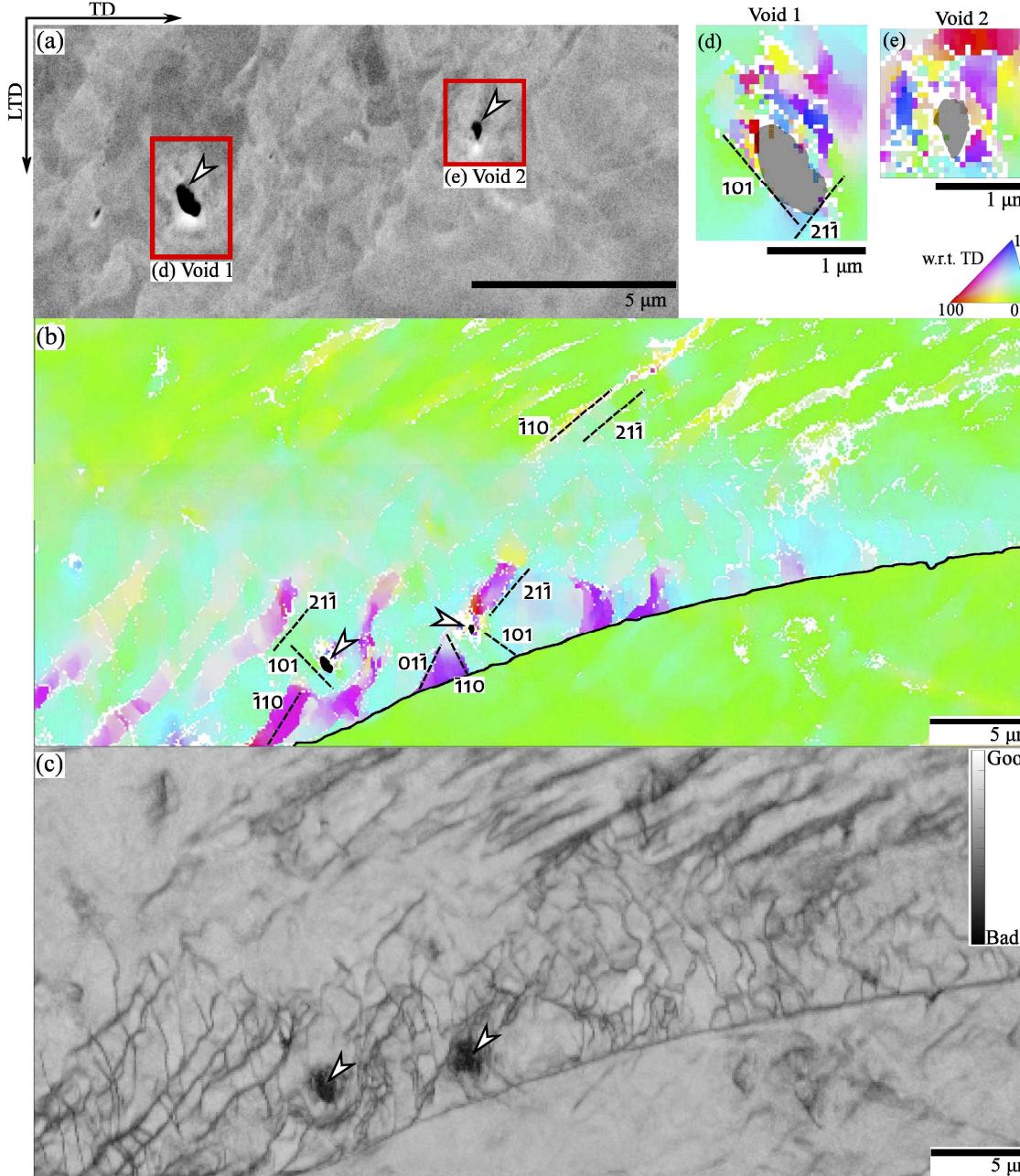


**Hypothesis:** void nucleation under tension in pure metals occurs when the dislocation network forms intense cell walls that are detected as high-angle subgrain boundaries.

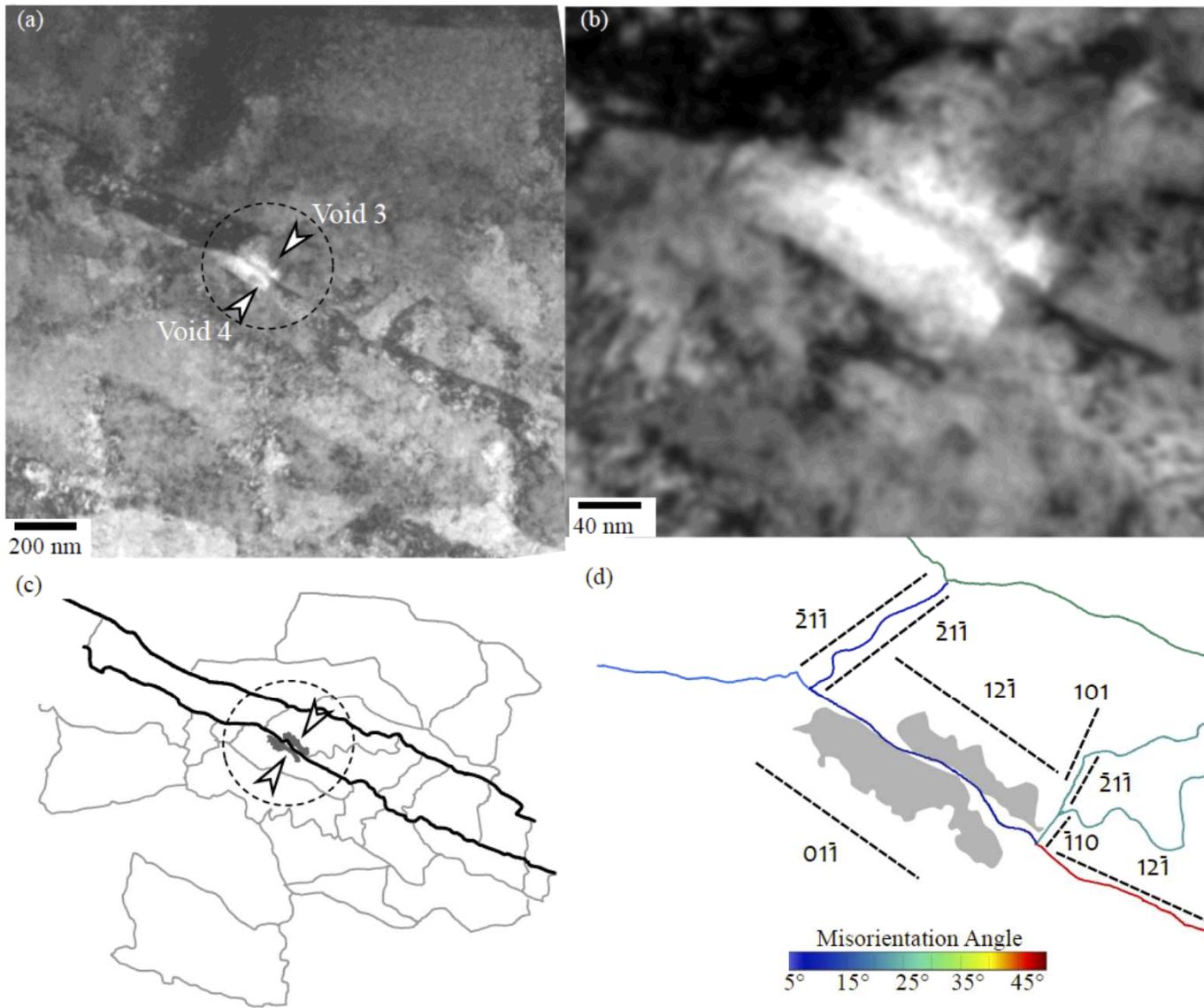
## ***Overview of Highly Deformed Necking Region...***



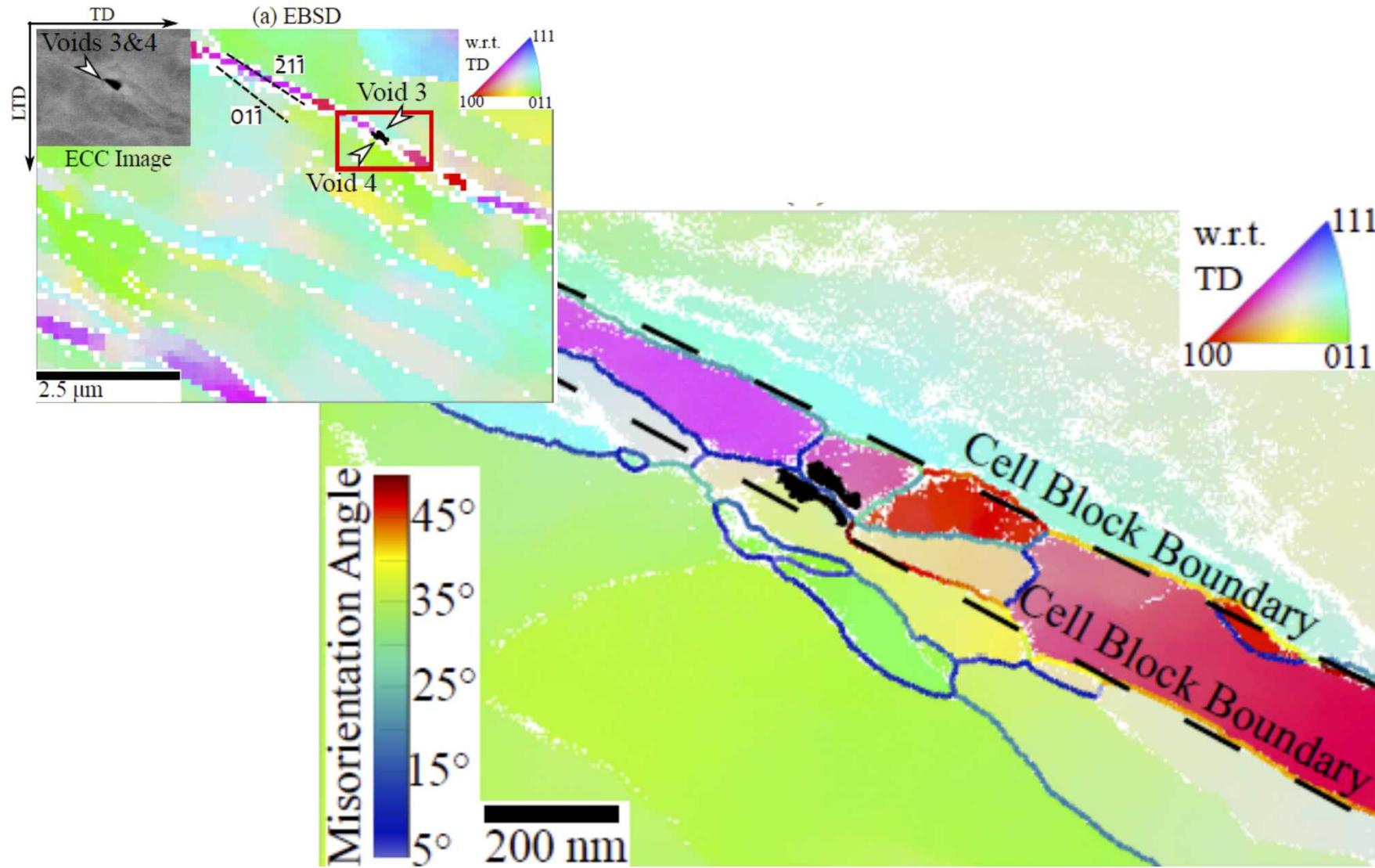
# Voids 1 and 2 at Cell Block Boundaries near a GB



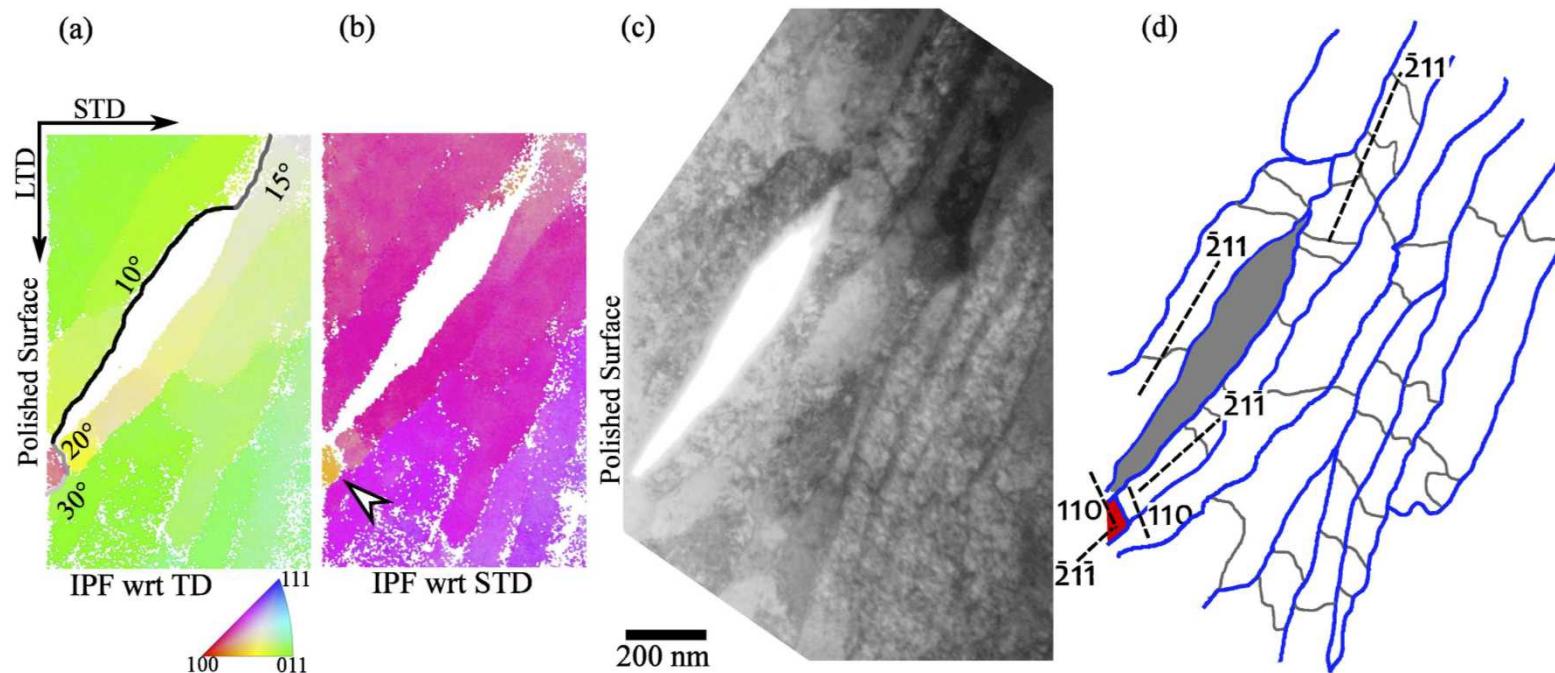
# Voids 3 and 4 at a Cell Block Boundary “Isthmus”



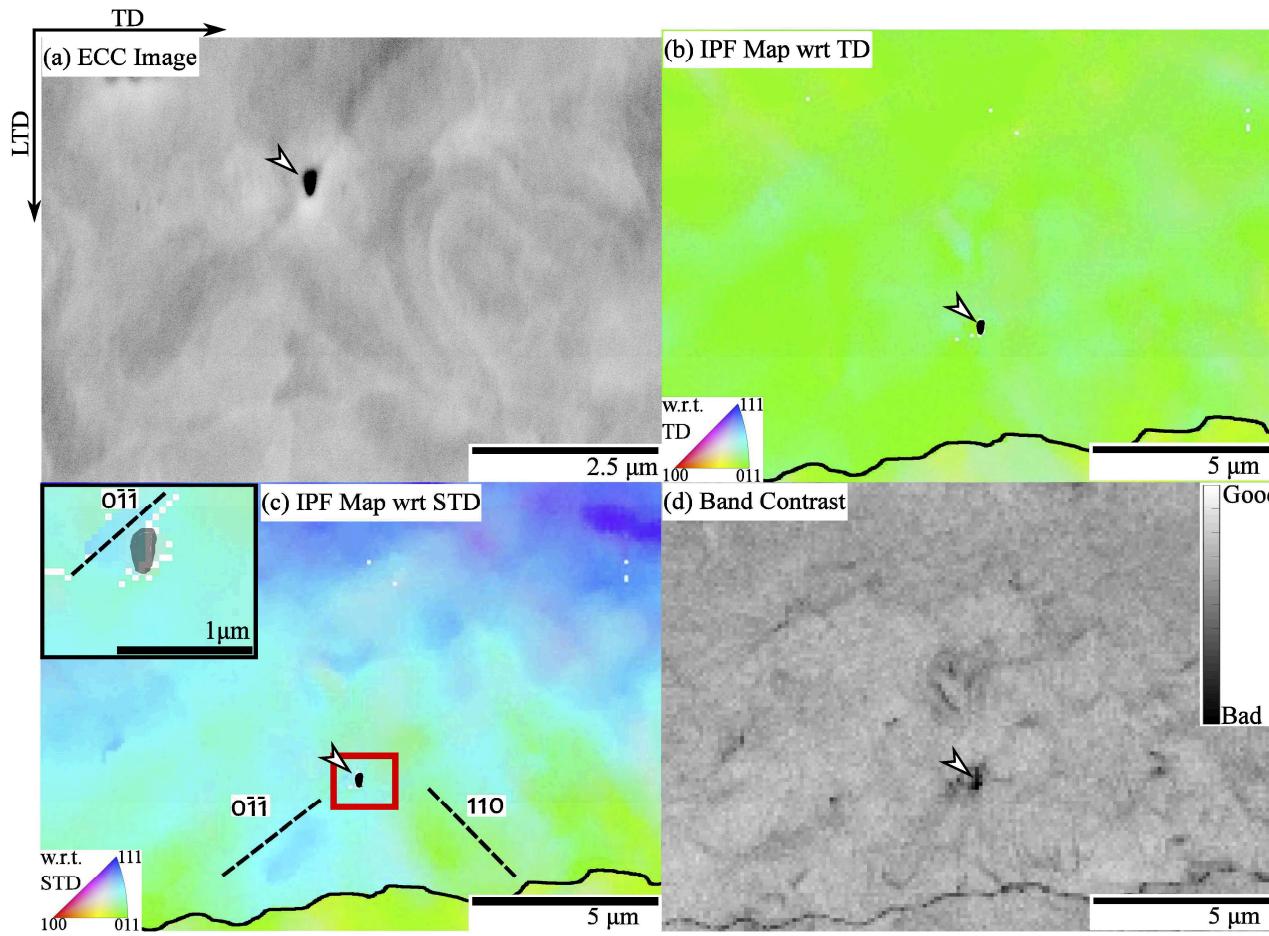
# Voids 3 and 4 at a Cell Block Boundary “Isthmus”



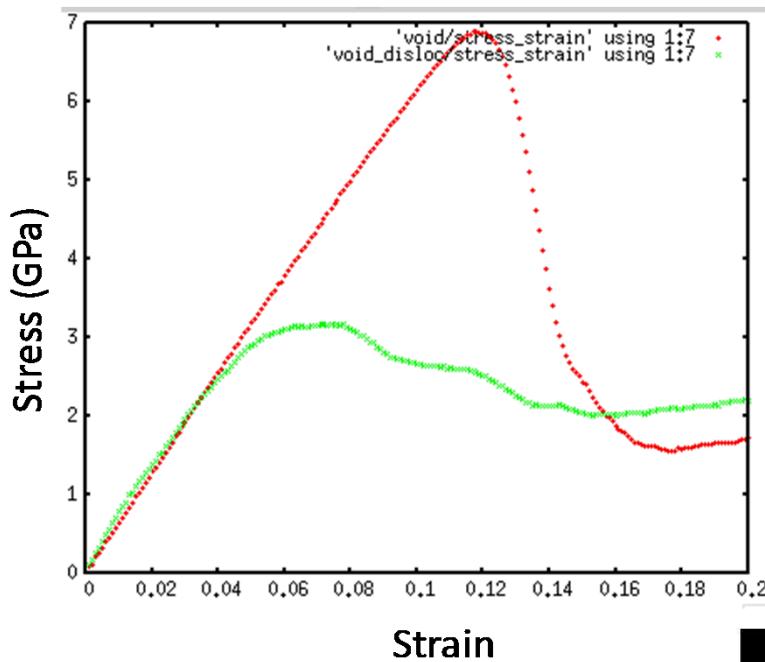
# Revisiting the “Treasure Hunt” Void



# *A few voids (2 of 20) did not seem to involve misorientation boundaries due to lack of subsurface (3D) data?*



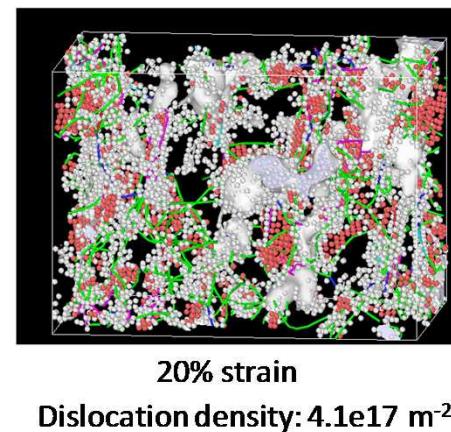
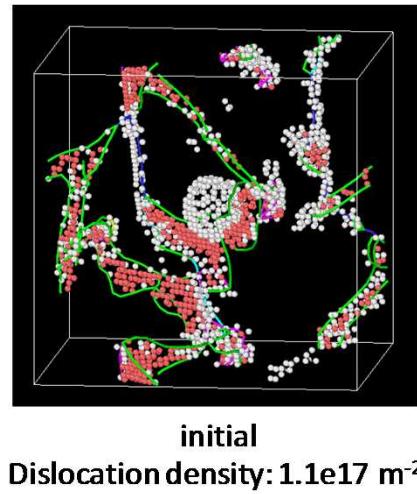
# Modeling Void Nucleation & Growth



- The classical theory for deformation-induced void growth is that voids grow by dislocation emission.
- Our work and others [Bringa et al, 2010] have shown that void growth by dislocation emission requires very large stresses  $\sim 7$  GPa

We hypothesize that voids grow by dislocation consumption

- Molecular Dynamics simulations are underway to assess the dislocation consumption hypothesis
- Experiments underway to assess the dislocation substructure in the vicinity of voids.



Under quasi-static loading, pure Ta forms incipient voids primarily at cell block wall boundaries.

Nucleation is often associated with an extensive local misorientation network

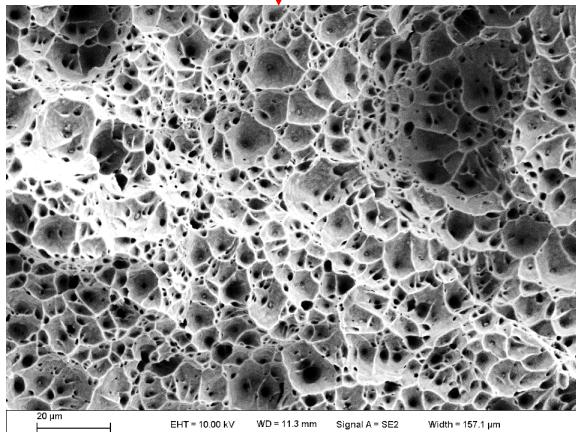
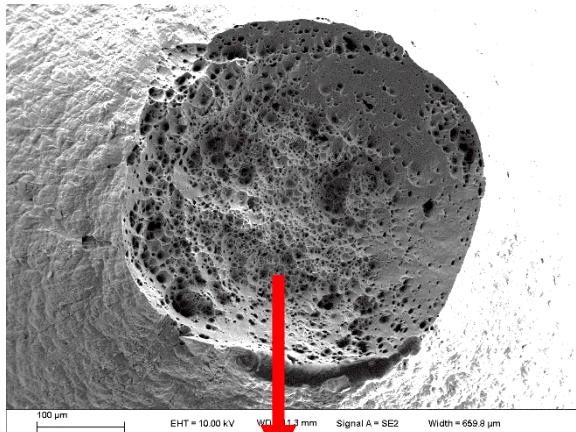
These highly deformed zones are often in the grain “mantle”, near but not at grain boundaries

Direct modeling by dislocation dynamics, crystal plasticity, or macroscale finite element would be difficult.

Molecular dynamics models suggest that certain dislocations impinging on Voids serve to facilitate growth...

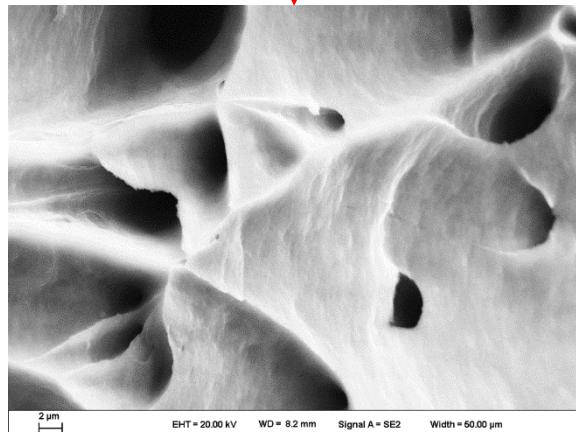
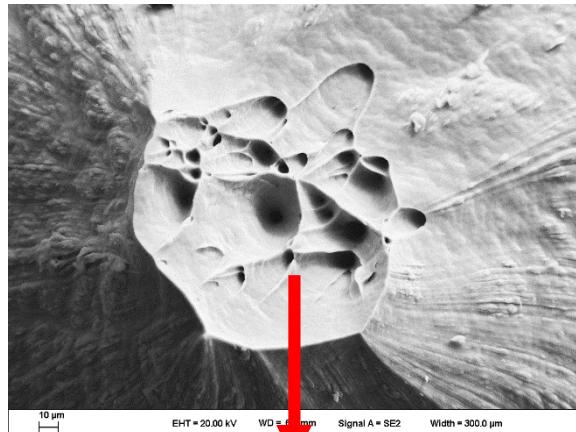
# Void morphology strongly depends on purity

99.9% Al



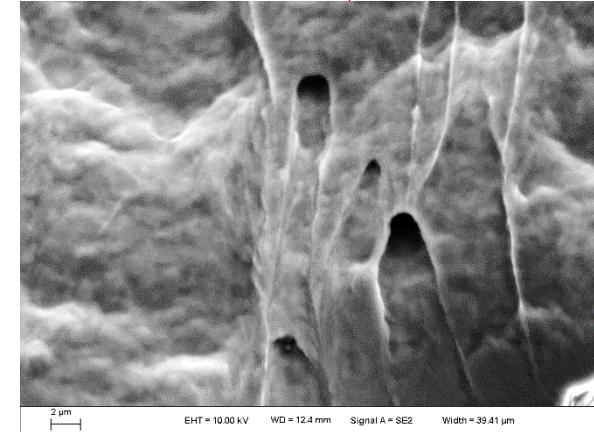
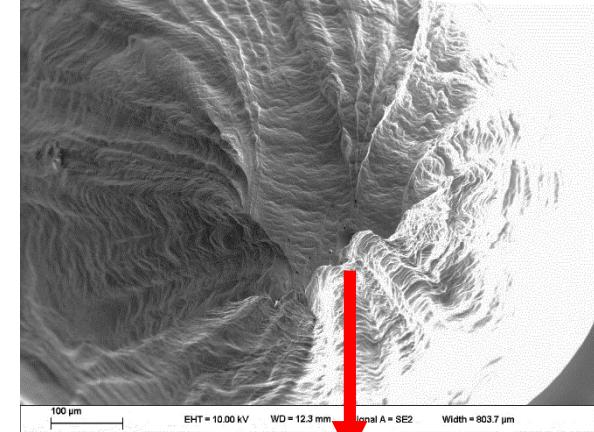
- Classic ductile dimples
- At least some void appear to nucleate at hard inclusions
- A potential case study for hard particle nucleation?

99.99% Al



- “goldilocks zone” for pure initiation?
- Avoids dynamic recrystallization & nucleation at inclusions

99.999% Al

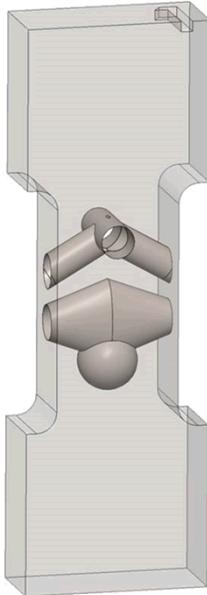


- Necking to a point (100% reduction in area)
- Only a few dimples at rupture
- Cross-sections reveal dynamic recrystallization

# Underway... The 3<sup>rd</sup> Sandia Fracture Challenge



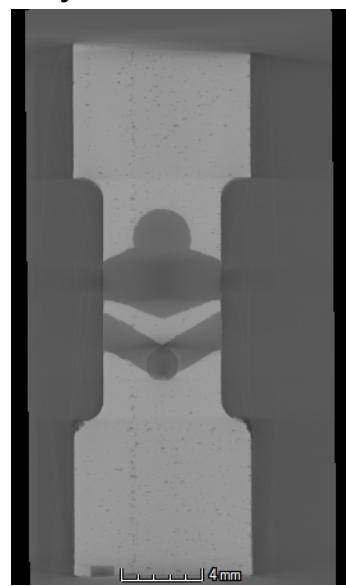
An additively manufactured structure with internal chambers that cannot be manufactured by conventional methods



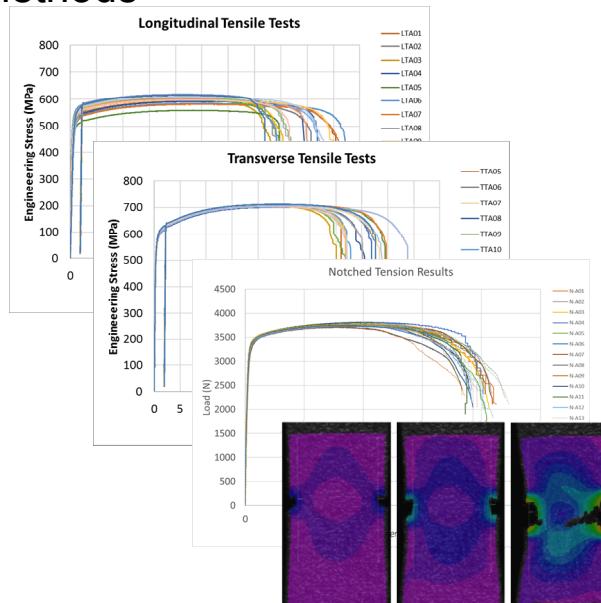
CAD



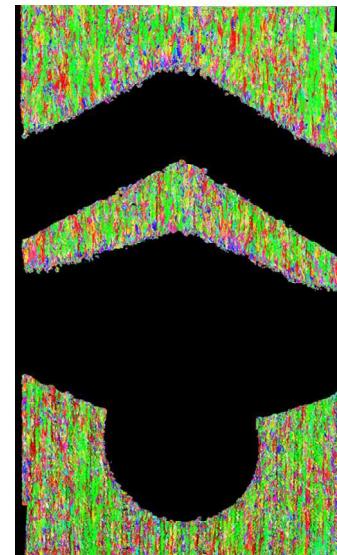
Optical Image



CT Scan showing internal porosity



Notch & smooth bar calibration data (with DIC) from the same build



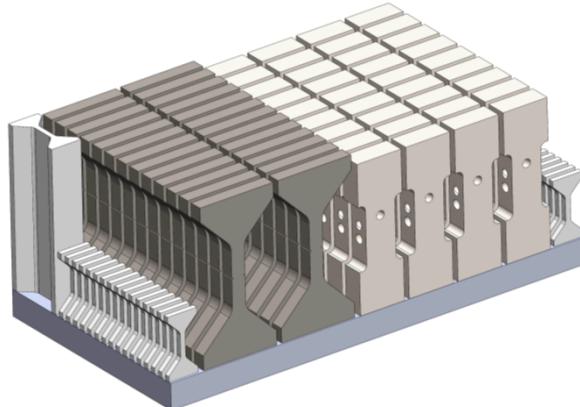
Microstructure & Texture data

**Provided the following engineering data...**

- x-ray CT scans
- tensile & notch tensile tests
- EBSD Microstructure, surface roughness, etc.

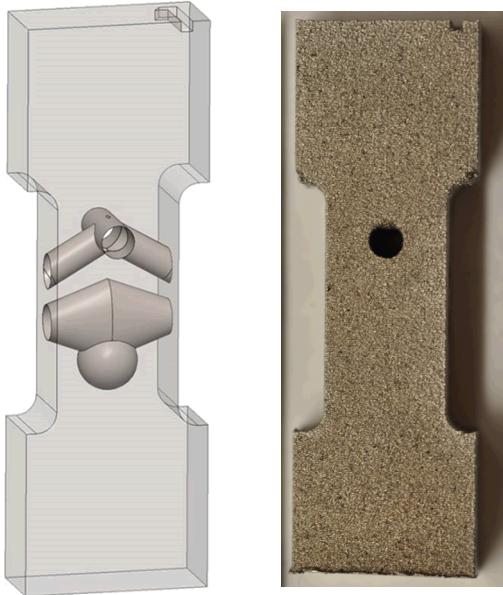
**Predict the variability in failure response...**

- location of crack initiation
- forces associated with crack initiation
- local surface strains during deformation



# Underway... The 3<sup>rd</sup> Sandia Fracture Challenge

An additively manufactured structure with internal chambers that cannot be manufactured by conventional methods



CAD

Optical Image

## Pre-registered Participants:

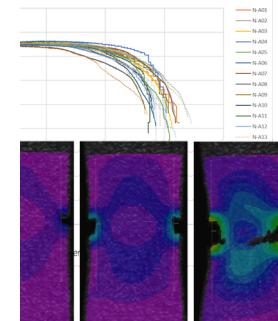
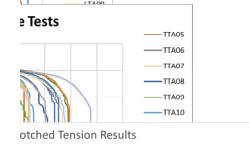
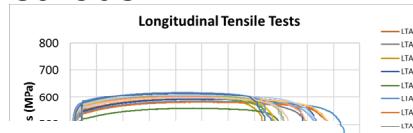
1. Sandia (3 teams)
2. Univ. of Texas-Austin
3. MIT
4. Purdue
5. Southwest Research Institute
6. Exponent
7. Pratt & Whitney
8. General Electric
9. Max-Planck Institute (Germany)
10. Univ. of Utah
11. OCAS NE (France)
12. RWTH Aachen (Germany)
13. Thinkviewer
14. Regensburg Univ. (Germany)
15. Kazimierz Wielki Univ. (Poland)
16. Tecnalia Research (Spain)
17. US Army Corps of Engineers
18. US Army ARDEC

## Provided the following engineering data:

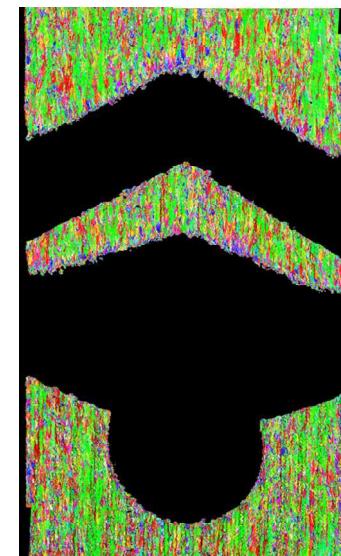
- x-ray CT scans
- tensile & notch tensile
- EBSD Microstructure,

## Predict the variability in fracture:

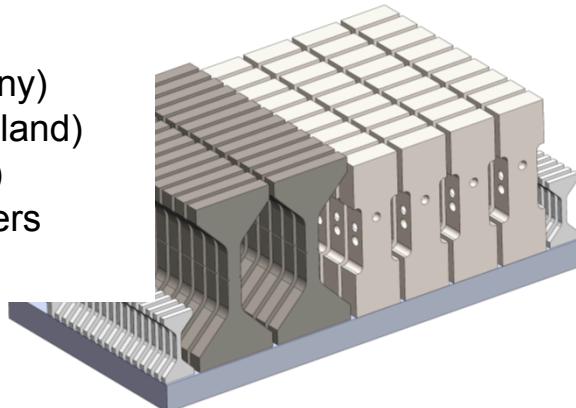
- location of crack initiation
- forces associated with crack initiation
- local surface strains during deformation



for calibration  
in the same build



Microstructure &  
Texture data



111

001

110



**The purpose of the Structural Reliability Partnership is to leverage expertise and investments from multiple institutions on areas of mutual interest in the domain of structural reliability.**

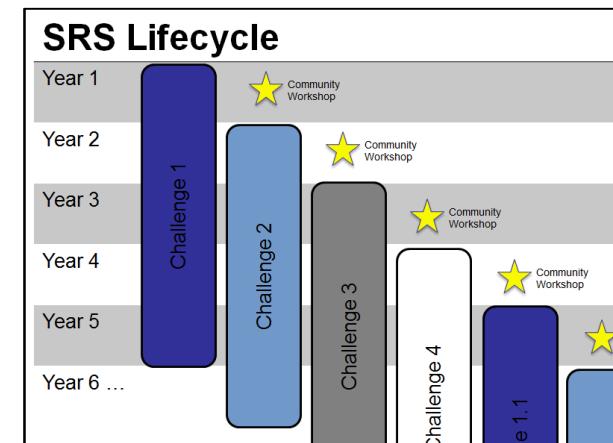
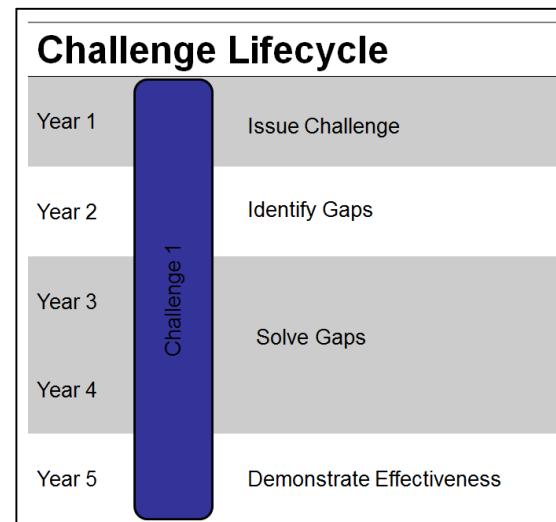
Preliminary pilot partners:



**Sandia  
National  
Laboratories**



**Massachusetts  
Institute of  
Technology**



## *Two general categories for material phenomena*

### **Homogeneous vs. Heterogeneous (Emergent / Weakest Link)**

(governed by average microstructure) (highly stochastic phenomena governed by a 'weak' feature in the microstructure)

Elasticity

Yield strength (engineering)

Thermal Conductivity

Electrical Conductivity

Magnetic Permeability

Ductile Rupture

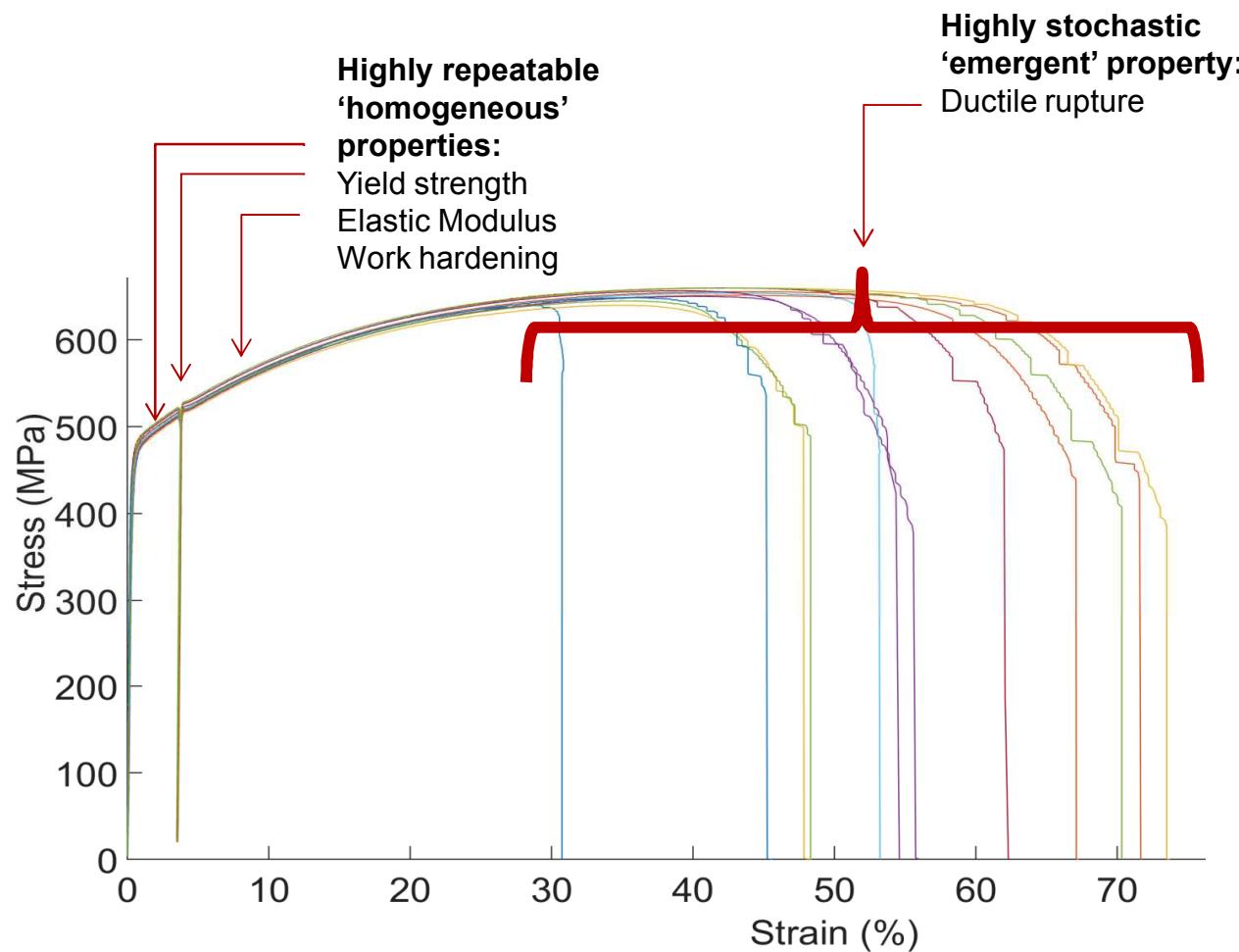
Corrosion Pit Initiation

Dielectric Breakdown

Creep Rupture

Nuclei in Solidification

## Heterogeneous “Emergent” Phenomena are Particularly Challenging for Material R



12 Nominally Identical Additively Manufactured 304L Tensile Bars Produced by NSC